

REMARKS

The foregoing amendment and the following arguments are provided to impart precision to the claims, by more particularly pointing out the invention, rather than to avoid prior art.

Claim Objections

Examiner objected to claims 17, 22 and 28 for reason of various informalities as outlined in the 09/18/2002 Office Action. These three claims have been amended as suggested by the Examiner in the interest of overcoming Examiner's objections.

35 U.S.C. § 102(e) Rejections

Examiner rejected claims 1-3, 5-6, 9-11, 13-14, 17-22, 24-26 and 28 are rejected under 35 USC 102(e) as being anticipated by Patel et al., U.S. Patent No. 6,418,017 B1 (hereinafter referred to as "Patel").

"To anticipate a claims, the reference must teach every element of the claim. A claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference." (Manual of Patent Examining Procedures (MPEP) ¶ 2131.)

Independent claims 1, 19, and 24 of the present application include limitations not disclosed or taught by Patel et al. As a result, claims 1, 19, and 24 are not anticipated by Patel et al.

In particular, independent claims 1, 19, and 24 include the limitation, or a limitation similar thereto, of a detachable thermo-siphon device formed as an integral

part of a wall of the chassis. Patel et al does not disclose or suggest the claimed detachable thermo-siphon device formed as an integral part of a wall of the chassis, as is claimed by applicant.

Rather, Patel et al discloses the use of a heat pipe that is not detachable from a wall of a chassis:

Prior art heat pipes are fabricated as units that are separate from chassis member 12. such separate heat pipes are mechanically fastened to chassis member 12, as by screws, clips, or other fastners, or by welding, soldering, epoxy or by way of fixtures or receptacles fastened to or incorporated into the surfaces of chassis members or bases. . . .

Clearly, Patel et al is teaching away from a detachable thermo-siphon, as is claimed by applicant. As a result, applicant's independent claims include limitations that are not disclosed nor suggested by Patel et al, and applicant's independent claims are therefore not anticipated by Patel et al.

Furthermore, the remaining claims depend from one of independent claims 1, 19, and 24, and therefore include the distinguishing claim limitations of claims 1, 19, and 24, as discussed above. As a result, the remaining claims are also not anticipated by Patel et al.

CONCLUSION

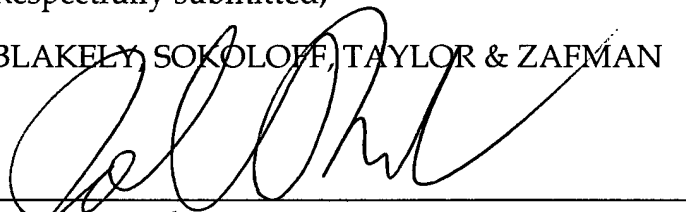
Applicant respectfully submits the present application is in condition for allowance. If the Examiner believes a telephone conference would expedite or

assist in the allowance of the present application, the Examiner is invited to call John Ward at (408) 720-8300, x237.

Authorization is hereby given to charge our Deposit Account No. 02-2666 for any charges that may be due.

Respectfully submitted,

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ATTACHMENT A

A marked-up version of the amended claims is as follows:

1. (Amended) A device enclosure comprising:
a chassis; and
a detachable thermo-siphon device formed as an integral part of a wall of the chassis.
2. The device of claim 1, wherein the device is an electronic device.
3. The device of claim 2, wherein the device enclosure is a computer chassis.
4. The device of claim 1, wherein the device is a non-electronic device.
5. The device of claim 1, wherein the thermo-siphon device is a heat pipe.
6. The device of claim 1, wherein the thermo-siphon device is a strip of a high efficiency conduit material.
9. The device of claim 1, wherein the wall is fabricated from a metallic material.
10. The device of claim 1, wherein the thermo-siphon device is embedded in a cavity of the wall.

11. The device of claim 10, wherein the cavity is created during a fabrication process of the wall.

12. The device of claim 1, wherein the wall partially encloses the thermo-siphon device.

13. The device of claim 12, wherein a portion of the thermo-siphon device is exposed to an interior of the enclosure.

14. The device of claim 12, wherein a portion of the thermo-siphon device is exposed to a heat sink.

17. (Amended) The device of claim 1, wherein the thermo-siphon device is secured to a wall cavity through the means selected from the group consisting of a support provided by cavity walls, a thermal epoxy, and an interference fit with the wall [skin] cavity.

18. The device of claim 1, wherein a metallic plate interfaces a heat source with the thermo-siphon device.

20. (Amended) A system comprising:
a chassis; and
a detachable thermo-siphon device formed as an integral part of a wall of the chassis.

20. The system of claim 19, wherein the thermo-siphon device is a heat pipe.

21. The system of claim 19, wherein the thermo-siphon device is a strip of high efficiency conduit material.

22. The system of claim 19, wherein the chassis is a computer [housing]chassis.

25. (Amended) A computer chassis comprising:

a chassis; and

a detachable thermo-siphon device formed as an integral part of a wall of the chassis.

25. The computer chassis of claim 24, wherein the thermo-siphon device is a heat pipe.

26. The computer chassis of claim 24, wherein the computer chassis is a notebook computer base.

28. The computer chassis of claim 24 [27], wherein the thermo-siphon device is embedded in the wall during the manufacturing process of the skin.